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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, LCD, POR, PWM, WDT
Number of I/O	51
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 21x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32l162rct6a

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Table 5. Functionalities depending on the working mode (from Run/active down to standby)

Ips	Run/Active	Sleep	Low-power Run	Low-power Sleep	Stop		Standby	
						Wakeup capability		Wakeup capability
CPU	Y	--	Y	--	--	--	--	--
Flash	Y	Y	Y	Y	--	--	--	--
RAM	Y	Y	Y	Y	Y	--	--	--
Backup Registers	Y	Y	Y	Y	Y	--	Y	--
EEPROM	Y	Y	Y	Y	Y	--	--	--
Brown-out rest (BOR)	Y	Y	Y	Y	Y	Y	Y	--
DMA	Y	Y	Y	Y	--	--	--	--
Programmable Voltage Detector (PVD)	Y	Y	Y	Y	Y	Y	Y	--
Power On Reset (POR)	Y	Y	Y	Y	Y	Y	Y	--
Power Down Rest (PDR)	Y	Y	Y	Y	Y	--	Y	--
High Speed Internal (HSI)	Y	Y	--	--	--	--	--	--
High Speed External (HSE)	Y	Y	--	--	--	--	--	--
Low Speed Internal (LSI)	Y	Y	Y	Y	Y	--	Y	--
Low Speed External (LSE)	Y	Y	Y	Y	Y	--	Y	--
Multi-Speed Internal (MSI)	Y	Y	Y	Y	--	--	--	--
Inter-Connect Controller	Y	Y	Y	Y	--	--	--	--
RTC	Y	Y	Y	Y	Y	Y	Y	--
RTC Tamper	Y	Y	Y	Y	Y	Y	Y	Y
Auto WakeUp (AWU)	Y	Y	Y	Y	Y	Y	Y	Y
LCD	Y	Y	Y	Y	Y	--	--	--
USB	Y	Y	--	--	--	Y	--	--
USART	Y	Y	Y	Y	Y	(1)	--	--
SPI	Y	Y	Y	Y	--	--	--	--
I2C	Y	Y	Y	Y	--	(1)	--	--

3.5 Low-power real-time clock and backup registers

The real-time clock (RTC) is an independent BCD timer/counter. Dedicated registers contain the sub-second, second, minute, hour (12/24 hour), week day, date, month, year, in BCD (binary-coded decimal) format. Correction for 28, 29 (leap year), 30, and 31 day of the month are made automatically. The RTC provides two programmable alarms and programmable periodic interrupts with wakeup from Stop and Standby modes.

The programmable wakeup time ranges from 120 µs to 36 hours.

The RTC can be calibrated with an external 512 Hz output, and a digital compensation circuit helps reduce drift due to crystal deviation.

The RTC can also be automatically corrected with a 50/60Hz stable powerline.

The RTC calendar can be updated on the fly down to sub second precision, which enables network system synchronization.

A time stamp can record an external event occurrence, and generates an interrupt.

There are thirty-two 32-bit backup registers provided to store 128 bytes of user application data. They are cleared in case of tamper detection.

Three pins can be used to detect tamper events. A change on one of these pins can reset backup register and generate an interrupt. To prevent false tamper event, like ESD event, these three tamper inputs can be digitally filtered.

3.6 GPIOs (general-purpose inputs/outputs)

Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are shared with digital or analog alternate functions, and can be individually remapped using dedicated AFIO registers. All GPIOs are high current capable. The alternate function configuration of I/Os can be locked if needed following a specific sequence in order to avoid spurious writing to the I/O registers. The I/O controller is connected to the AHB with a toggling speed of up to 16 MHz.

External interrupt/event controller (EXTI)

The external interrupt/event controller consists of 24 edge detector lines used to generate interrupt/event requests. Each line can be individually configured to select the trigger event (rising edge, falling edge, both) and can be masked independently. A pending register maintains the status of the interrupt requests. The EXTI can detect an external line with a pulse width shorter than the Internal APB2 clock period. Up to 115 GPIOs can be connected to the 16 external interrupt lines. The 8 other lines are connected to RTC, PVD, USB, comparator events or capacitive sensing acquisition.

event chaining. Their counter can be frozen in debug mode. Any of the general-purpose timers can be used to generate PWM outputs.

TIM2, TIM3, TIM4, TIM5 all have independent DMA request generation.

These timers are capable of handling quadrature (incremental) encoder signals and the digital outputs from 1 to 3 hall-effect sensors.

TIM10, TIM11 and TIM9

TIM10 and TIM11 are based on a 16-bit auto-reload upcounter. TIM9 is based on a 16-bit auto-reload up/down counter. They include a 16-bit prescaler. TIM10 and TIM11 feature one independent channel, whereas TIM9 has two independent channels for input capture/output compare, PWM or one-pulse mode output. They can be synchronized with the TIM2, TIM3, TIM4, TIM5 full-featured general-purpose timers.

They can also be used as simple time bases and be clocked by the LSE clock source (32.768 kHz) to provide time bases independent from the main CPU clock.

3.17.2 Basic timers (TIM6 and TIM7)

These timers are mainly used for DAC trigger generation. They can also be used as generic 16-bit time bases.

3.17.3 SysTick timer

This timer is dedicated to the OS, but could also be used as a standard downcounter. It is based on a 24-bit downcounter with autoreload capability and a programmable clock source. It features a maskable system interrupt generation when the counter reaches 0.

3.17.4 Independent watchdog (IWDG)

The independent watchdog is based on a 12-bit downcounter and 8-bit prescaler. It is clocked from an independent 37 kHz internal RC and, as it operates independently of the main clock, it can operate in Stop and Standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management. It is hardware- or software-configurable through the option bytes. The counter can be frozen in debug mode.

3.17.5 Window watchdog (WWDG)

The window watchdog is based on a 7-bit downcounter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

3.18 Communication interfaces

3.18.1 I²C bus

Up to two I²C bus interfaces can operate in multimaster and slave modes. They can support standard and fast modes.

Table 8. STM32L162xC/C-A pin definitions (continued)

Pins					Pin name	Pin Type(1)	I / O structure	Main function(2) (after reset)	Pin functions	
LQFP144	UFBGA132	LQFP100	LQFP64	WLCSP64					Alternate functions	Additional functions
96	E12	63	37	E1	PC6	I/O	FT	PC6	TIM3_CH1/I2S2_MCK/ LCD_SEG24	-
97	E11	64	38	E2	PC7	I/O	FT	PC7	TIM3_CH2/I2S3_MCK/ LCD_SEG25	-
98	E10	65	39	E3	PC8	I/O	FT	PC8	TIM3_CH3/LCD_SEG26	-
99	D12	66	40	D1	PC9	I/O	FT	PC9	TIM3_CH4/LCD_SEG27	-
100	D11	67	41	E4	PA8	I/O	FT	PA8	USART1_CK/MCO/ LCD_COM0	-
101	D10	68	42	D2	PA9	I/O	FT	PA9	USART1_TX / LCD_COM1	-
102	C12	69	43	D3	PA10	I/O	FT	PA10	USART1_RX / LCD_COM2	-
103	B12	70	44	C1	PA11	I/O	FT	PA11	USART1_CTS/ SPI1_MISO	USB_DM
104	A12	71	45	C2	PA12	I/O	FT	PA12	USART1_RTS/ SPI1_MOSI	USB_DP
105	A11	72	46	D4	PA13	I/O	FT	JTMS-SWDIO	JTMS-SWDIO	-
106	C11	73	-	-	PH2	I/O	FT	PH2	-	-
107	F11	74	47	B1	V_{SS_2}	S	-	V_{SS_2}	-	-
108	G11	75	48	A1	V_{DD_2}	S	-	V_{DD_2}	-	-
109	A10	76	49	B2	PA14	I/O	FT	JTCK-SWCLK	JTCK-SWCLK	-
110	A9	77	50	C3	PA15	I/O	FT	JTDI	TIM2_CH1_ETR/ SPI1_NSS/SPI3_NSS/ I2S3_WS/LCD_SEG17/ JTDI	-
111	B11	78	51	A2	PC10	I/O	FT	PC10	SPI3_SCK/I2S3_CK/ USART3_TX/ LCD_SEG28/LCD_SEG40/ LCD_COM4	-
112	C10	79	52	B3	PC11	I/O	FT	PC11	SPI3_MISO/USART3_RX/ LCD_SEG29/LCD_SEG41/ LCD_COM5	-

Table 9. Alternate function input/output (continued)

Port name	Digital alternate function number														
	AFIO0	AFIO1	AFIO2	AFIO3	AFIO4	AFIO5	AFIO6	AFIO7	AFIO8	..	AFIO11	AFIO12	..	AFIO14	AFIO15
	Alternate function														
	SYSTEM	TIM2	TIM3/4/5	TIM9/ 10/11	I2C1/2	SPI1/2	SPI3	USART1/2/3	-		LCD	-		CPRI	SYSTEM
PE7	-	-	-	-	-	-	-	-	-		-			TIMx_IC4	EVENT OUT
PE8	-	-	-	-	-	-	-	-	-		-			TIMx_IC1	EVENT OUT
PE9	-	TIM2_CH1_ETR	-	-	-	-	-	-	-		-			TIMx_IC2	EVENT OUT
PE10	-	TIM2_CH2	-	-	-	-	-	-	-		-			TIMx_IC3	EVENT OUT
PE11	-	TIM2_CH3	-	-	-	-	-	-	-		-			TIMx_IC4	EVENT OUT
PE12	-	TIM2_CH4	-	-	-	SPI1_NSS	-	-	-		-			TIMx_IC1	EVENT OUT
PE13	-	-	-	-	-	SPI1_SCK	-	-	-		-			TIMx_IC2	EVENT OUT
PE14	-	-	-	-	-	SPI1_MISO	-	-	-		-			TIMx_IC3	EVENT OUT
PE15	-	-	-	-	-	SPI1_MOSI	-	-	-		-			TIMx_IC4	EVENT OUT
PF0	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF1	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF2	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF3	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF4	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF5	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT

Table 9. Alternate function input/output (continued)

Port name	Digital alternate function number														
	AFIO0	AFIO1	AFIO2	AFIO3	AFIO4	AFIO5	AFIO6	AFIO7	AFIO8	..	AFIO11	AFIO12	..	AFIO14	AFIO15
	Alternate function														
	SYSTEM	TIM2	TIM3/4/5	TIM9/ 10/11	I2C1/2	SPI1/2	SPI3	USART1/2/3	-		LCD	-		CPRI	SYSTEM
PF6	-	-	TIM5_ETR	-	-	-	-	-	-		-	-		-	EVENT OUT
PF7	-	-	TIM5_CH2	-	-	-	-	-	-		-	-		-	EVENT OUT
PF8	-	-	TIM5_CH3	-	-	-	-	-	-		-	-		-	EVENT OUT
PF9	-	-	TIM5_CH4	-	-	-	-	-	-		-	-		-	EVENT OUT
PF10	-	-	-	-	-	-	-	-	-		-	-		-	EVENT OUT
PF11	-	-	-	-	-	-	-	-	-		-	-		-	EVENT OUT
PF12	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF13	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF14	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PF15	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PG0	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PG1	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PG2	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PG3	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT
PG4	-	-	-	-	-	-	-	-	-		-			-	EVENT OUT

6.3.3 Embedded internal reference voltage

The parameters given in *Table 16* are based on characterization results, unless otherwise specified.

Table 15. Embedded internal reference voltage calibration values

Calibration value name	Description	Memory address
VREFINT_CAL	Raw data acquired at temperature of 30 °C ±5 °C V_{DDA}= 3 V ±10 mV	0x1FF8 00F8 - 0x1FF8 00F9

Table 16. Embedded internal reference voltage

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{REFINT\ out}$ (1)	Internal reference voltage	– 40 °C < T_J < +110 °C	1.202	1.224	1.242	V
I_{REFINT}	Internal reference current consumption	-	-	1.4	2.3	µA
$T_{VREFINT}$	Internal reference startup time	-	-	2	3	ms
V_{VREF_MEAS}	V_{DDA} and V_{REF+} voltage during V_{REFINT} factory measure	-	2.99	3	3.01	V
A_{VREF_MEAS}	Accuracy of factory-measured V_{REF} value(2)	Including uncertainties due to ADC and V_{DDA}/V_{REF+} values	-	-	±5	mV
T_{Coeff}(3)	Temperature coefficient	–40 °C < T_J < +110 °C	-	25	100	ppm/°C
A_{Coeff}(3)	Long-term stability	1000 hours, T= 25 °C	-	-	1000	ppm
$V_{DDCoeff}$(3)	Voltage coefficient	3.0 V < V_{DDA} < 3.6 V	-	-	2000	ppm/V
$T_{S\_vrefint}$(3)	ADC sampling time when reading the internal reference voltage	-	4	-	-	µs
T_{ADC_BUF}(3)	Startup time of reference voltage buffer for ADC	-	-	-	10	µs
I_{BUF_ADC}(3)	Consumption of reference voltage buffer for ADC	-	-	13.5	25	µA
I_{VREF_OUT}(3)	VREF_OUT output current (4)	-	-	-	1	µA
C_{VREF_OUT}(3)	VREF_OUT output load	-	-	-	50	pF
I_{LPBUF}(3)	Consumption of reference voltage buffer for VREF_OUT and COMP	-	-	730	1200	nA
V_{REFINT_DIV1}(3)	1/4 reference voltage	-	24	25	26	% V_{REFINT}
V_{REFINT_DIV2}(3)	1/2 reference voltage	-	49	50	51	
V_{REFINT_DIV3}(3)	3/4 reference voltage	-	74	75	76	

1. Guaranteed by test in production.
2. The internal V_{REF} value is individually measured in production and stored in dedicated EEPROM bytes.
3. Guaranteed by characterization results.
4. To guarantee less than 1% VREF_OUT deviation.

Table 21. Current consumption in Low-power sleep mode

Symbol	Parameter	Conditions			Typ	Max(1)	Unit
I_{DD} (LP Sleep)	Supply current in Low-power sleep mode	All peripherals OFF, V_{DD} from 1.65 V to 3.6 V	MSI clock, 65 kHz f_{HCLK} = 32 kHz Flash OFF	T_A = -40 °C to 25 °C	4.4	-	µA
			MSI clock, 65 kHz f_{HCLK} = 32 kHz Flash ON	T_A = -40 °C to 25 °C	18	21	
				T_A = 85 °C	24	27	
				T_A = 105 °C	35	43	
			MSI clock, 65 kHz f_{HCLK} = 65 kHz, Flash ON	T_A = -40 °C to 25 °C	18.6	21	
				T_A = 85 °C	24.5	28	
				T_A = 105 °C	35	42	
			MSI clock, 131 kHz f_{HCLK} = 131 kHz, Flash ON	T_A = -40 °C to 25 °C	22	25	
				T_A = 55 °C	23.5	26	
				T_A = 85 °C	28.5	31	
				T_A = 105 °C	39	45	
		TIM9 and USART1 enabled, Flash ON, V_{DD} from 1.65 V to 3.6 V	MSI clock, 65 kHz f_{HCLK} = 32 kHz	T_A = -40 °C to 25 °C	18	20.5	
				T_A = 85 °C	24	27	
				T_A = 105 °C	35	43	
			MSI clock, 65 kHz f_{HCLK} = 65 kHz	T_A = -40 °C to 25 °C	18.6	21	
				T_A = 85 °C	24.5	28	
				T_A = 105 °C	35	42	
			MSI clock, 131 kHz f_{HCLK} = 131 kHz	T_A = -40 °C to 25 °C	22	25	
				T_A = 55 °C	23.5	26	
				T_A = 85 °C	28.5	31	
				T_A = 105 °C	39	45	
I_{DD} max (LP Sleep)	Max allowed current in Low-power sleep mode	V_{DD} from 1.65 V to 3.6 V	-	-	-	200	

1. Guaranteed by characterization results, unless otherwise specified.

Table 22. Typical and maximum current consumptions in Stop mode

Symbol	Parameter	Conditions			Typ	Max(1)	Unit
I_{DD} (Stop with RTC)	Supply current in Stop mode with RTC enabled	RTC clocked by LSI or LSE external clock (32.768kHz), regulator in LP mode, HSI and HSE OFF (no independent watchdog)	LCD OFF	T_A = -40°C to 25°C V_{DD} = 1.8 V	1.1	-	µA
				T_A = -40°C to 25°C	1.35	4	
				T_A = 55°C	1.95	6	
				T_A= 85°C	4.35	10	
				T_A = 105°C	11.0	23	
			LCD ON (static duty)(2)	T_A = -40°C to 25°C	1.65	6	
				T_A = 55°C	2.1	7	
				T_A= 85°C	4.7	12	
				T_A = 105°C	11.0	27	
			LCD ON (1/8 duty)(3)	T_A = -40°C to 25°C	2.5	10	
				T_A = 55°C	4.65	11	
				T_A= 85°C	7.25	16	
				T_A = 105°C	14.0	44	
		RTC clocked by LSE external quartz (32.768kHz), regulator in LP mode, HSI and HSE OFF (no independent watchdog(4)	LCD OFF	T_A = -40°C to 25°C	1.7	-	
				T_A = 55°C	2.15	-	
				T_A= 85°C	4.7	-	
				T_A = 105°C	11.5	-	
			LCD ON (static duty)(2)	T_A = -40°C to 25°C	1.8	-	
				T_A = 55°C	2.35	-	
				T_A= 85°C	4.85	-	
				T_A = 105°C	11.5	-	
			LCD ON (1/8 duty)(3)	T_A = -40°C to 25°C	2.45	-	
				T_A = 55°C	4.9	-	
				T_A= 85°C	7.7	-	
				T_A = 105°C	14.5	-	
			LCD OFF	T_A = -40°C to 25°C V_{DD} = 1.8V	1.35	-	
				T_A = -40°C to 25°C V_{DD} = 3.0V	1.7	-	
				T_A = -40°C to 25°C V_{DD} = 3.6V	2.0	-	

Static latch-up

Two complementary static tests are required on six parts to assess the latch-up performance:

- A supply overvoltage is applied to each power supply pin
- A current injection is applied to each input, output and configurable I/O pin

These tests are compliant with EIA/JESD 78A IC latch-up standard.

Table 40. Electrical sensitivities

Symbol	Parameter	Conditions	Class
LU	Static latch-up class	T_A = +105 °C conforming to JESD78A	II level A

6.3.12 I/O current injection characteristics

As a general rule, current injection to the I/O pins, due to external voltage below V_{SS} or above V_{DD} (for standard pins) should be avoided during normal product operation. However, in order to give an indication of the robustness of the microcontroller in cases when abnormal injection accidentally happens, susceptibility tests are performed on a sample basis during device characterization.

Functional susceptibility to I/O current injection

While a simple application is executed on the device, the device is stressed by injecting current into the I/O pins programmed in floating input mode. While current is injected into the I/O pin, one at a time, the device is checked for functional failures.

The failure is indicated by an out of range parameter: ADC error above a certain limit (higher than 5 LSB TUE), out of conventional limits of induced leakage current on adjacent pins (out of –5 µA/+0 µA range), or other functional failure (for example reset occurrence oscillator frequency deviation, LCD levels).

The test results are given in the *Table 41*.

Table 41. I/O current injection susceptibility

Symbol	Description	Functional susceptibility		Unit
		Negative injection	Positive injection	
I_{INJ}	Injected current on all 5 V tolerant (FT) pins	-5 (1)	NA	mA
	Injected current on BOOT0	-0	NA	
	Injected current on any other pin	-5 (1)	+5	

1. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative currents.

Output driving current

The GPIOs (general purpose input/outputs) can sink or source up to ±8 mA, and sink or source up to ±20 mA with the non-standard V_{OL}/V_{OH} specifications given in *Table 43*.

In the user application, the number of I/O pins which can drive current must be limited to respect the absolute maximum rating specified in *Section 6.2*:

- The sum of the currents sourced by all the I/Os on $V_{DD,}$ plus the maximum Run consumption of the MCU sourced on $V_{DD,}$ cannot exceed the absolute maximum rating $I_{VDD(\Sigma)}$ (see *Table 11*).
- The sum of the currents sunk by all the I/Os on V_{SS} plus the maximum Run consumption of the MCU sunk on V_{SS} cannot exceed the absolute maximum rating $I_{VSS(\Sigma)}$ (see *Table 11*).

Output voltage levels

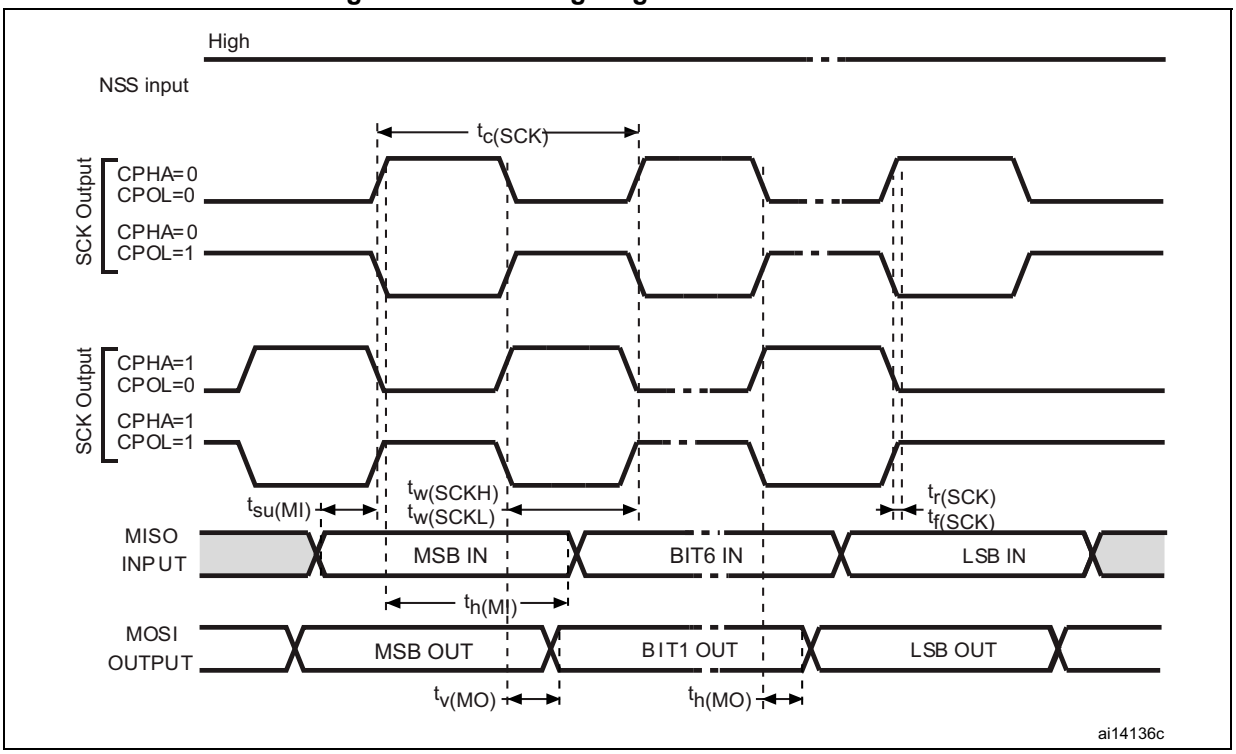
Unless otherwise specified, the parameters given in *Table 43* are derived from tests performed under the conditions summarized in *Table 13*. All I/Os are CMOS and TTL compliant.

Table 43. Output voltage characteristics

Symbol	Parameter	Conditions	Min	Max	Unit
V_{OL} (1)(2)	Output low level voltage for an I/O pin	I_{IO} = 8 mA 2.7 V < V_{DD} < 3.6 V	-	0.4	V
V_{OH} (2)(3)	Output high level voltage for an I/O pin		V_{DD}-0.4	-	
V_{OL} (3)(4)	Output low level voltage for an I/O pin	I_{IO} = 4 mA 1.65 V < V_{DD} < 3.6 V	-	0.45	
V_{OH} (3)(4)	Output high level voltage for an I/O pin		V_{DD}-0.45	-	
V_{OL} (1)(4)	Output low level voltage for an I/O pin	I_{IO} = 20 mA 2.7 V < V_{DD} < 3.6 V	-	1.3	
V_{OH} (3)(4)	Output high level voltage for an I/O pin		V_{DD}-1.3	-	

1. The I_{IO} current sunk by the device must always respect the absolute maximum rating specified in *Table 11* and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VSS}.
2. Guaranteed by test in production.
3. The I_{IO} current sourced by the device must always respect the absolute maximum rating specified in *Table 11* and the sum of I_{IO} (I/O ports and control pins) must not exceed I_{VDD}.
4. Guaranteed by characterization results.

Figure 22. SPI timing diagram - master mode(1)



1. Measurement points are done at CMOS levels: $0.3V_{DD}$ and $0.7V_{DD}$.

Table 55. ADC characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_S (5)	Sampling time	Direct channels 2.4 V ≤V_{DDA} ≤3.6 V	0.25	-	-	µs
		Multiplexed channels 2.4 V ≤V_{DDA} ≤3.6 V	0.56	-	-	
		Direct channels 1.8 V ≤V_{DDA} ≤2.4 V	0.56	-	-	
		Multiplexed channels 1.8 V ≤V_{DDA} ≤2.4 V	1	-	-	
		-	4	-	384	$1/f_{ADC}$
t_{CONV}	Total conversion time (including sampling time)	f_{ADC} = 16 MHz	1	-	24.75	µs
		-	4 to 384 (sampling phase) +12 (successive approximation)			$1/f_{ADC}$
C_{ADC}	Internal sample and hold capacitor	Direct channels	-	16	-	pF
		Multiplexed channels	-		-	
f_{TRIG}	External trigger frequency Regular sequencer	12-bit conversions	-	-	Tconv+1	$1/f_{ADC}$
		6/8/10-bit conversions	-	-	Tconv	$1/f_{ADC}$
f_{TRIG}	External trigger frequency Injected sequencer	12-bit conversions	-	-	Tconv+2	$1/f_{ADC}$
		6/8/10-bit conversions	-	-	Tconv+1	$1/f_{ADC}$
R_{AIN} (6)	Signal source impedance		-	-	50	kΩ
t_{lat}	Injection trigger conversion latency	f_{ADC} = 16 MHz	219	-	281	ns
		-	3.5	-	4.5	$1/f_{ADC}$
t_{latr}	Regular trigger conversion latency	f_{ADC} = 16 MHz	156	-	219	ns
		-	2.5	-	3.5	$1/f_{ADC}$
t_{STAB}	Power-up time	-	-	-	3.5	µs

1. The Vref+ input can be grounded if neither the ADC nor the DAC are used (this allows to shut down an external voltage reference).
2. The current consumption through VREF is composed of two parameters:

   - one constant (max 300 µA)

   - one variable (max 400 µA), only during sampling time + 2 first conversion pulses

   So, peak consumption is 300+400 = 700 µA and average consumption is 300 + [(4 sampling + 2) /16] x 400 = 450 µA at 1Msps
3. V_{REF+} can be internally connected to V_{DDA} and V_{REF-} can be internally connected to V_{SSA}, depending on the package. Refer to *Section 4: Pin descriptions* for further details.
4. V_{SSA} or V_{REF-} must be tied to ground.
5. Minimum sampling time is reached for an external input impedance limited to a value as defined in *Table 57: Maximum source impedance RAIN max*.
6. External impedance has another high value limitation when using short sampling time as defined in *Table 57: Maximum source impedance RAIN max*.

6.3.18 DAC electrical specifications

Data guaranteed by design, unless otherwise specified.

Table 58. DAC characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DDA}	Analog supply voltage	-	1.8	-	3.6	V
V_{REF+}	Reference supply voltage	V_{REF+} must always be below V_{DDA}	1.8	-	3.6	
V_{REF-}	Lower reference voltage	-	V_{SSA}			
$I_{DDVREF+}$(1)	Current consumption on V_{REF+} supply V_{REF+} = 3.3 V	No load, middle code (0x800)	-	130	220	µA
		No load, worst code (0x000)	-	220	350	
I_{DDA}(1)	Current consumption on V_{DDA} supply V_{DDA} = 3.3 V	No load, middle code (0x800)	-	210	320	
		No load, worst code (0xF1C)	-	320	520	
R_L(2)	Resistive load	DAC output buffer ON	5	-	-	kΩ
C_L(2)	Capacitive load		-	-	50	pF
R_O	Output impedance	DAC output buffer OFF	12	16	20	kΩ
V_{DAC_OUT}	Voltage on DAC_OUT output	DAC output buffer ON	0.2	-	V_{DDA} – 0.2	V
		DAC output buffer OFF	0.5	-	V_{REF+} – 1LSB	mV
DNL(1)	Differential non linearity(3)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	1.5	3	LSB
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	1.5	3	
INL(1)	Integral non linearity(4)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	2	4	
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	2	4	
Offset(1)	Offset error at code 0x800 (5)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	±10	±25	
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	±5	±8	
Offset1(1)	Offset error at code 0x001(6)	No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	±1.5	±5	

Table 58. DAC characteristics (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
dOffset/dT(1)	Offset error temperature coefficient (code 0x800)	V_{DDA} = 3.3V V_{REF+} = 3.0V T_A = 0 to 50 °C DAC output buffer OFF	-20	-10	0	µV/°C
		V_{DDA} = 3.3V V_{REF+} = 3.0V T_A = 0 to 50 °C DAC output buffer ON	0	20	50	
Gain(1)	Gain error(7)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	+0.1 / -0.2%	+0.2 / -0.5%	%
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	+0 / -0.2%	+0 / -0.4%	
dGain/dT(1)	Gain error temperature coefficient	V_{DDA} = 3.3V V_{REF+} = 3.0V T_A = 0 to 50 °C DAC output buffer OFF	-10	-2	0	µV/°C
		V_{DDA} = 3.3V V_{REF+} = 3.0V T_A = 0 to 50 °C DAC output buffer ON	-40	-8	0	
TUE(1)	Total unadjusted error	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ DAC output buffer ON	-	12	30	LSB
		No R_L, $C_L \leq 50$ pF DAC output buffer OFF	-	8	12	
$t_{SETTLING}$	Settling time (full scale: for a 12-bit code transition between the lowest and the highest input codes till DAC_OUT reaches final value ±1LSB	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ	-	7	12	µs
Update rate	Max frequency for a correct DAC_OUT change (95% of final value) with 1 LSB variation in the input code	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ	-	-	1	Msps
t_{WAKEUP}	Wakeup time from off state (setting the ENx bit in the DAC Control register)(8)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ	-	9	15	µs
PSRR+	V_{DDA} supply rejection ratio (static DC measurement)	$C_L \leq 50$ pF, $R_L \geq 5$ kΩ	-	-60	-35	dB

1. Data based on characterization results.
2. Connected between DAC_OUT and V_{SSA}.
3. Difference between two consecutive codes - 1 LSB.

1. Guaranteed by characterization results.
2. The delay is characterized for 100 mV input step with 10 mV overdrive on the inverting input, the non-inverting input set to the reference.
3. Comparator consumption only. Internal reference voltage not included.

Table 63. Comparator 2 characteristics

Symbol	Parameter	Conditions	Min	Typ	Max(1)	Unit
V_{DDA}	Analog supply voltage	-	1.65	-	3.6	V
V_{IN}	Comparator 2 input voltage range	-	0	-	V_{DDA}	V
t_{START}	Comparator startup time	Fast mode	-	15	20	µs
		Slow mode	-	20	25	
$t_{d\ slow}$	Propagation delay(2) in slow mode	1.65 V ≤V_{DDA} ≤2.7 V	-	1.8	3.5	
		2.7 V ≤V_{DDA} ≤3.6 V	-	2.5	6	
$t_{d\ fast}$	Propagation delay(2) in fast mode	1.65 V ≤V_{DDA} ≤2.7 V	-	0.8	2	
		2.7 V ≤V_{DDA} ≤3.6 V	-	1.2	4	
V_{offset}	Comparator offset error		-	±4	±20	mV
dThreshold/ dt	Threshold voltage temperature coefficient	V_{DDA} = 3.3V T_A = 0 to 50 °C V- =V_{REFINT}, 3/4 V_{REFINT}, 1/2 V_{REFINT}, 1/4 V_{REFINT}.	-	15	100	ppm /°C
I_{COMP2}	Current consumption(3)	Fast mode	-	3.5	5	µA
		Slow mode	-	0.5	2	

1. Guaranteed by characterization results.
2. The delay is characterized for 100 mV input step with 10 mV overdrive on the inverting input, the non-inverting input set to the reference.
3. Comparator consumption only. Internal reference voltage (necessary for comparator operation) is not included.

Table 65. LQFP144, 20 x 20 mm, 144-pin low-profile quad flat package mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	21.800	22.000	22.200	0.8583	0.8661	0.8740
D1	19.800	20.000	20.200	0.7795	0.7874	0.7953
D3	-	17.500	-	-	0.6890	-
E	21.800	22.000	22.200	0.8583	0.8661	0.8740
E1	19.800	20.000	20.200	0.7795	0.7874	0.7953
E3	-	17.500	-	-	0.6890	-
e	-	0.500	-	-	0.0197	-
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
k	0°	3.5°	7°	0°	3.5°	7°
ccc	-	-	0.080	-	-	0.0031

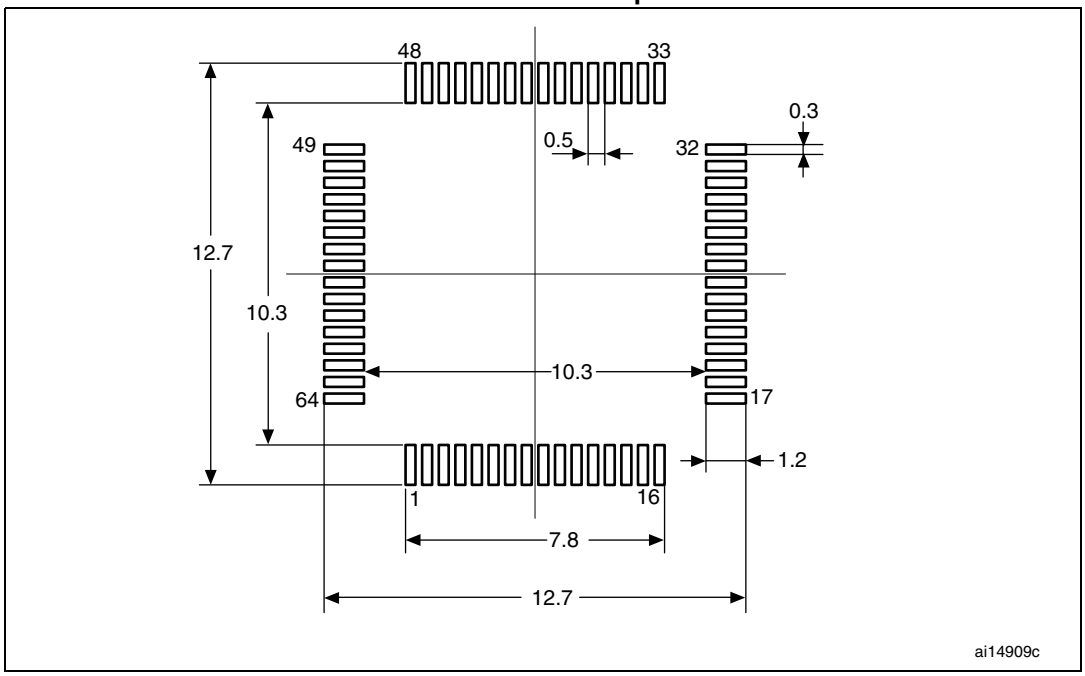
1. Values in inches are converted from mm and rounded to 4 decimal digits.

Table 67. LQFP64, 10 x 10 mm 64-pin low-profile quad flat package mechanical data (continued)

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
E3	-	7.500	-	-	0.2953	-
e	-	0.500	-	-	0.0197	-
K	0°	3.5°	7°	0°	3.5°	7°
L	0.450	0.600	0.750	0.0177	0.0236	0.0295
L1	-	1.000	-	-	0.0394	-
ccc	-	-	0.080	-	-	0.0031

1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 37. LQFP64, 10 x 10 mm, 64-pin low-profile quad flat package recommended footprint



1. Dimensions are in millimeters.

8 Part numbering

Table 70. STM32L162xC/C-A ordering information scheme

Example: STM32 L 162 R C T 6 A D TR

Device family

STM32 = ARM-based 32-bit microcontroller

Product type

L = Low-power

Device subfamily

162: Devices with LCD

Pin count

R = 64 pins

V = 100 pins

Z = 144 pins

Q = 132 pins

Flash memory size

C = 256 Kbytes of Flash memory

Package

H = BGA

T = LQFP

Temperature range

6 = Industrial temperature range, –40 to 85 °C

7 = Industrial temperature range, –40 to 105 °C

Identification code

A = Proprietary identification code

Blank = No proprietary identification code

Options

No character = V_{DD} range: 1.8 to 3.6 V and BOR enabled

D = V_{DD} range: 1.65 to 3.6 V and BOR disabled

Packing

TR = tape and reel

No character = tray or tube

For a list of available options (speed, package, etc.) or for further information on any aspect of this device, please contact the nearest ST sales office.